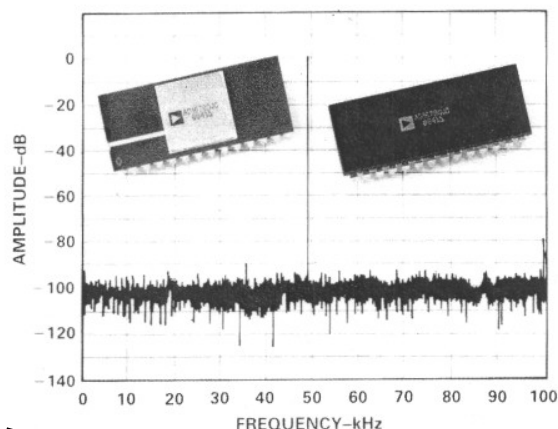


### FEATURES

AC Characterized and Specified  
 200k Conversions per Second  
 1MHz Full Power Bandwidth  
 500kHz Full Linear Bandwidth  
 72dB S/N+D (K Grade)  
 Twos Complement Data Format (Bipolar Mode)  
 Straight Binary Data Format (Unipolar Mode)  
 10M $\Omega$  Input Impedance  
 8 Bit or 16-Bit Bus Interface  
 On-Board Reference and Clock  
 10V Unipolar or Bipolar Input Range



### PRODUCT DESCRIPTION

The AD1678 is a 12-bit monolithic analog-to-digital converter, consisting of a sample-and-hold amplifier (SHA), a microprocessor compatible bus interface, a voltage reference and clock generation circuitry.

This product is fabricated on Analog Devices' BiMOS process, combining low power CMOS logic with high precision, low noise bipolar circuits; laser-trimmed thin-film resistors provide high accuracy. The converter utilizes a recursive subranging algorithm which includes error correction and flash converter circuitry to achieve high speed and resolution.

The AD1678 is specified for ac (or "dynamic") parameters such as S/N+D ratio, THD and IMD. These parameters are important in signal processing applications as they indicate the AD1678's effect on the spectral content of the input signal. The AD1678 offers a choice of digital interface formats; the 12 data bits can be accessed by a 16-bit bus in a single read operation or by an 8-bit bus in two read operations (8+4), with right or left justification. Data format is straight binary for unipolar mode and twos complement binary for bipolar mode. The input has a full-scale range of 10V with a full power bandwidth of 1 MHz and a full linear bandwidth of 500kHz. High input impedance (10M $\Omega$ ) allows direct connection to unbuffered sources without signal degradation.

The AD1678 operates from +5V and  $\pm 12$ V supplies and dissipates 600mW. A 28-pin plastic DIP and a 0.6" wide ceramic DIP are available. Contact factory for surface-mount package options.

### PRODUCT HIGHLIGHTS

- 1. PERFORMANCE:** The AD1678 provides a throughput of 200k conversions per second. S/N+D is 72dB (K grade) at 10kHz and remains flat to beyond the Nyquist frequency.
- 2. INTEGRATION:** The AD1678 minimizes external component requirements by combining high speed sample-and-hold amplifier (SHA), ADC, 5V reference, clock and digital interface on a single chip. This provides a fully specified sampling A/D function unattainable with discrete designs.
- 3. EASE OF USE:** The pinout is designed for easy board layout, and the choice of single or two read cycle output provides compatibility with 16- or 8-bit buses. Factory trimming eliminates the need for calibration modes or external trimming to achieve rated performance.
- 4. RELIABILITY:** The AD1678 utilizes Analog Devices' monolithic low power BiMOS technology. This ensures long term reliability compared to multichip and hybrid designs.

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# AC SPECIFICATIONS ( $T_{\min}$ to $T_{\max}$ , $V_{CC}=+12V$ , $V_{EE}=-12V$ , $V_{DD}=+5V$ , $f_{\text{SAMPLE}}=200\text{KSPS}$ , $f_{\text{IN}}=10.06\text{kHz}$ )<sup>1</sup>

Model	AD1678J			AD1678K			Units
	Min	Typ	Max	Min	Typ	Max	
SIGNAL-TO-NOISE AND DISTORTION (S/N+D) RATIO <sup>2</sup> @ +25° C $T_{\min}$ to $T_{\max}$	70	71		72	73		dB
	70	71		71	73		dB
TOTAL HARMONIC DISTORTION (THD) <sup>3</sup> @ +25°C  $T_{\min}$ to $T_{\max}$		-88	-80		-88	-80	dB
		0.004	0.010		0.004	0.010	%
		-85	-78		-85	-78	dB
		0.005	0.012		0.005	0.012	%
PEAK SPURIOUS OR PEAK HARMONIC COMPONENT		-87	-80		-87	-80	dB
FULL POWER BANDWIDTH		1			1		MHz
FULL LINEAR BANDWIDTH		500			500		kHz
INTERMODULATION DISTORTION (IMD) <sup>4</sup> 2nd Order Products 3rd Order Products		-85	-80		-85	-80	dB
		-90	-80		-90	-80	dB

## NOTES

<sup>1</sup> $f_{\text{IN}}$  amplitude = -0.5dB (9.44V p-p) bipolar mode full scale unless otherwise indicated. All measurements referred to a 0dB (9.907V p-p) input signal.

<sup>2</sup>See Figures 2 and 3 for higher frequencies and other input amplitudes.

<sup>3</sup>See Figure 1 for other conditions.

<sup>4</sup> $f_A = 9.06\text{kHz}$ ,  $f_B = 9.58\text{kHz}$ , with  $f_{\text{SAMPLE}} = 200\text{KSPS}$ . See Figure 5 and Definition of Specifications section.

Specifications subject to change without notice.

# DIGITAL SPECIFICATIONS (for all grades $T_{\min}$ to $T_{\max}$ , $V_{CC}=+12V$ , $V_{EE}=-12V$ , $V_{DD}=+5V \pm 10\%$ )

Specification	Test Conditions	Min	Max	Units
LOGIC INPUTS				
$V_{\text{IH}}$ High Level Input Voltage		2.0		V
$V_{\text{IL}}$ Low Level Input Voltage			0.8	V
$I_{\text{IH}}$ High Level Input Current	$V_{\text{IN}} = 5V$		10	$\mu\text{A}$
$I_{\text{IL}}$ Low Level Input Current	$V_{\text{IN}} = 0V$		10	$\mu\text{A}$
$C_{\text{IN}}$ Input Capacitance			10	pF
LOGIC OUTPUTS				
$V_{\text{OH}}$ High Level Output Voltage	$I_{\text{OH}} = 0.5\text{mA}$	4.0		V
$V_{\text{OL}}$ Low Level Output Voltage	$I_{\text{OL}} = 1.6\text{mA}$		0.4	V
$I_{\text{OZ}}$ High Z Leakage Current	$V_{\text{IN}} = 0$ or $5V$		10	$\mu\text{A}$

## NOTE

Specifications shown in **boldface** are tested on all devices at final electrical test. Results from those tests are used to calculate outgoing quality levels.

All min and max specifications are guaranteed, although only those shown in boldface are tested.

Specifications subject to change without notice.

# DC SPECIFICATIONS

(@ +25°C,  $V_{CC}=+12V$ ,  $V_{EE}=-12V$ ,  $V_{DD}=+5V$  unless otherwise indicated)

Model	AD1678J			AD1678K			Units
	Min	Typ	Max	Min	Typ	Max	
ACCURACY							
Resolution	12			12			Bits
Differential Linearity							
T <sub>min</sub> to T <sub>max</sub> (No Missing Codes)	12			12			Bits
Unipolar Zero Error <sup>1</sup>		±4			±4		LSB
Bipolar Zero Error <sup>1</sup>		±4			±4		LSB
Unipolar Gain Error <sup>1,2</sup>		±3			±3		LSB
Bipolar Gain Error <sup>1,2</sup>		±3			±3		LSB
Temperature Drift (Coefficients) <sup>3</sup>							
Unipolar Zero		±2 (10)			±2 (10)		LSB (ppm/°C)
Bipolar Zero		±2 (10)			±2 (10)		LSB (ppm/°C)
Unipolar Gain		±4 (20)			±4 (20)		LSB (ppm/°C)
Bipolar Gain		±4 (20)			±4 (20)		LSB (ppm/°C)
ANALOG INPUT							
Input Ranges							
Unipolar Mode	0		+10	0		+10	V
Bipolar Mode	-5		+5	-5		+5	V
Input Resistance		10			10		MΩ
Input Capacitance (f <sub>IN</sub> = 100kHz)		10			10		pF
Input Settling Time			1			1	μs
Aperture Delay	5		20	5		20	ns
Aperture Jitter		150			150		ps
INTERNAL REFERENCE VOLTAGE							
Output Voltage <sup>4</sup>	4.95		5.05	4.95		5.05	V
External Load							
Unipolar Mode			+1.5			+1.5	mA
Bipolar Mode			+0.5			+0.5	mA
POWER SUPPLIES (T <sub>min</sub> to T <sub>max</sub> )							
Operating Voltages							
V <sub>CC</sub>	+11.4	+12	+12.6	+11.4	+12	+12.6	V
V <sub>EE</sub>	-12.6	-12	-11.4	-12.6	-12	-11.4	V
V <sub>DD</sub>	+4.5	+5	+5.5	+4.5	+5	+5.5	V
Operating Current							
I <sub>CC</sub>		17	19		17	19	mA
I <sub>EE</sub>		24	26		24	26	mA
I <sub>DD</sub>		5	10		5	10	mA
Power Consumption			600			600	mW

## NOTES

<sup>1</sup>Adjustable to zero; see Figures 8 and 9.

<sup>2</sup>Includes internal voltage reference error.

<sup>3</sup>Includes internal voltage reference drift.

<sup>4</sup>With maximum external load applied.

Specifications shown in **boldface** are tested on all devices at final electrical test. Results from those tests are used to calculate outgoing quality levels. All min and max specifications are guaranteed, although only those shown in boldface are tested.

Specifications subject to change without notice.



# Dynamic Performance

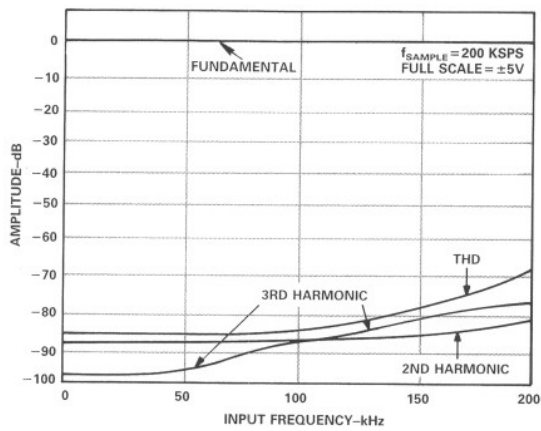


Figure 1. Harmonic Distortion vs. Input Frequency

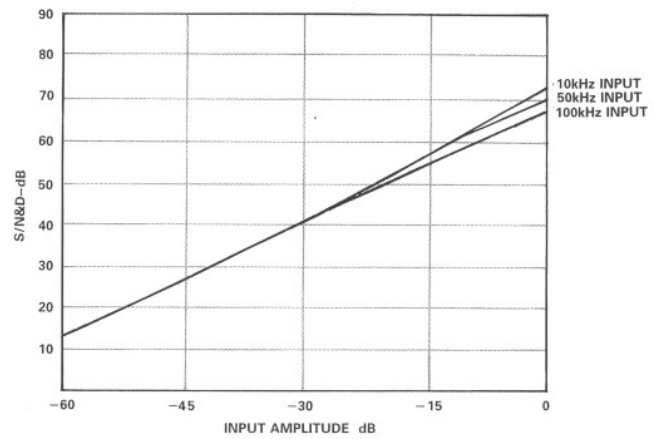


Figure 2. S/N&D vs. Input Amplitude ( $f_{\text{SAMPLE}} = 200\text{KSPS}$ )

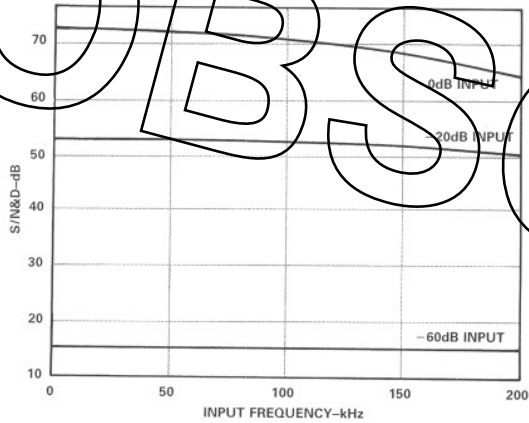


Figure 3. S/N&D vs. Input Frequency and Amplitude

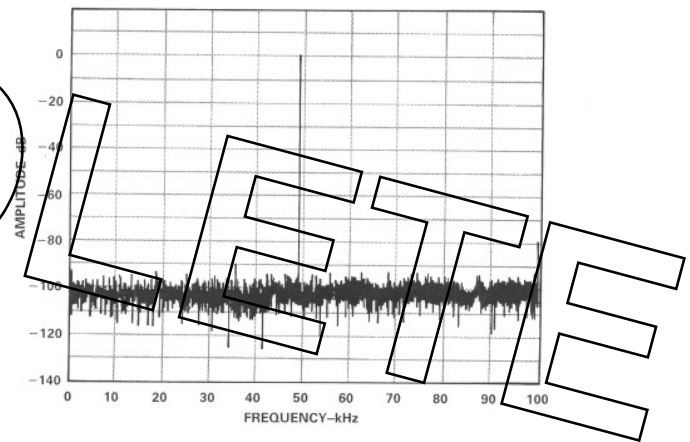


Figure 4. Nonaveraged 2048 Point FFT at 200KSPS,  $F_{\text{IN}} = 49.902\text{kHz}$

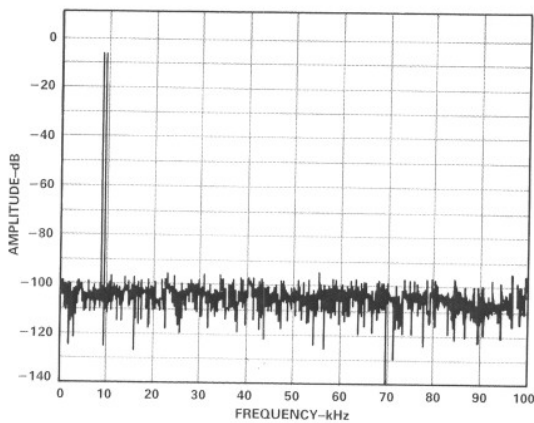


Figure 5. IMD Plot for  $F_{\text{IN}} = 9.08\text{kHz}$  ( $f_a$ ),  $9.58\text{kHz}$  ( $f_b$ )

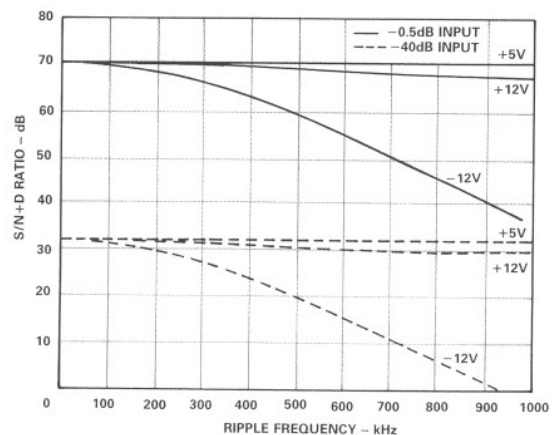


Figure 6. Power Supply Rejection ( $f_{\text{IN}} = 10\text{kHz}$ ,  $f_{\text{SAMPLE}} = 200\text{KSPS}$ ,  $V_{\text{RIPPLE}} = 0.1\text{V p-p}$ )

## FREQUENCY DOMAIN TESTING

The AD1678 is tested dynamically using a sine wave input and a 2048 point Fast Fourier Transform (FFT) to analyze the resulting output. Coherent sampling is used, wherein the ADC sampling frequency and the analog input frequency are related to each other by a ratio of integers. This ensures that an integral multiple of input cycles is captured, allowing direct FFT processing without windowing or digital filtering which could mask some of the dynamic characteristics of the device. In addition, the frequencies are chosen to be "relatively prime" (no common factors) to maximize the number of different ADC codes that are present in a sample sequence. The result, called Prime Coherent Sampling, is a highly accurate and repeatable measure of the actual frequency domain response of the converter.

## NYQUIST FREQUENCY

An implication of the Nyquist sampling theorem, the "Nyquist Frequency" of a converter, is that input frequency which is one-half the sampling frequency of the converter.

## SIGNAL-TO-NOISE AND DISTORTION (S/N+D) RATIO

S/N+D is the ratio of the rms value of the measured input signal to the rms sum of all other spectral components below the Nyquist frequency, including harmonics but excluding dc. The value for S/N+D is expressed in decibels.

## TOTAL HARMONIC DISTORTION (THD)

THD is the ratio of the rms sum of the first six harmonic components to the rms value of the measured input signal and is expressed as a percentage or in decibels. For input signals or harmonics that are above the Nyquist frequency, the aliased component is used.

## PEAK SPURIOUS OR PEAK HARMONIC COMPONENT

The peak spurious or peak harmonic component is the largest spectral component excluding the input signal and dc. This value is expressed in decibels relative to the measured input signal.

## INTERMODULATION DISTORTION (IMD)

With inputs consisting of sine waves at two frequencies,  $f_a$  and  $f_b$ , any device with nonlinearities will create distortion products, of order  $(m+n)$ , at sum and difference frequencies of  $m f_a \pm n f_b$ , where  $m, n = 0, 1, 2, 3 \dots$ . Intermodulation terms are those for which  $m$  or  $n$  is not equal to zero. For example, the second order terms are  $(f_a + f_b)$  and  $(f_a - f_b)$  and the third order terms are  $(2f_a + f_b)$ ,  $(2f_a - f_b)$ ,  $(f_a + 2f_b)$  and  $(f_a - 2f_b)$ . The IMD products are expressed as the decibel ratio of the RMS sum of the measured input signals to the RMS sum of the distortion terms. The two signals applied to the converter are of equal amplitude and the peak value of their sum is  $-0.5\text{dB}$  from full scale (9.44V p-p). The IMD products are normalized to a 0dB input signal.

## BANDWIDTH

The full-power bandwidth is that input frequency at which the amplitude of the reconstructed fundamental is reduced by 3dB for a full-scale input.

The full-linear bandwidth is the input frequency at which the slew rate limit of the sample-and-hold amplifier (SHA) is reached. At this point, the full-scale fundamental has degraded by less than  $-0.1\text{dB}$ . Beyond this frequency, distortion of the sampled input signal increases significantly.

The AD1678 has been designed to optimize input bandwidth, allowing the AD1678 to undersample input signals with frequencies significantly above the converter's Nyquist frequency. If the input signal is suitably band-limited, the spectral content of the input signal can be recovered. Examples of applications in which this technique is used include direct digitization of audio-modulated IF signals and doppler-shift measurements.

## APERTURE DELAY

Aperture delay is a measure of the SHA's performance and is measured from the falling edge of the Start Convert ( $\overline{SC}$ ) to when the input signal is held for conversion. In synchronous mode, Chip Select ( $\overline{CS}$ ) should be LOW before  $\overline{SC}$  to minimize aperture delay.

## APERTURE JITTER

Aperture jitter is the variation in aperture delay for successive samples and is manifested as noise on the input to the A/D.

## INPUT SETTling TIME

Settling time is a function of the SHA's ability to track fast slewing signals. This is specified as the maximum time required in track mode after a full-scale step input to guarantee rated conversion accuracy.

## DIFFERENTIAL NONLINEARITY (DNL)

In an ideal ADC, code transitions are 1 LSB apart. Differential nonlinearity is the deviation from this ideal value. It is often specified in terms of resolution for which no missing codes are guaranteed.

For the AD1678, this specification is 12 bits from  $T_{\min}$  to  $T_{\max}$ , which guarantees that all 4096 codes are present over temperature.

## UNIPOLAR ZERO ERROR

In unipolar mode, the first transition should occur at a level  $1/2$  LSB above analog ground. Unipolar zero error is the deviation of the actual transition from that point. This error can be adjusted as discussed in the Input Connections and Calibration Section.

## BIPOLAR ZERO ERROR

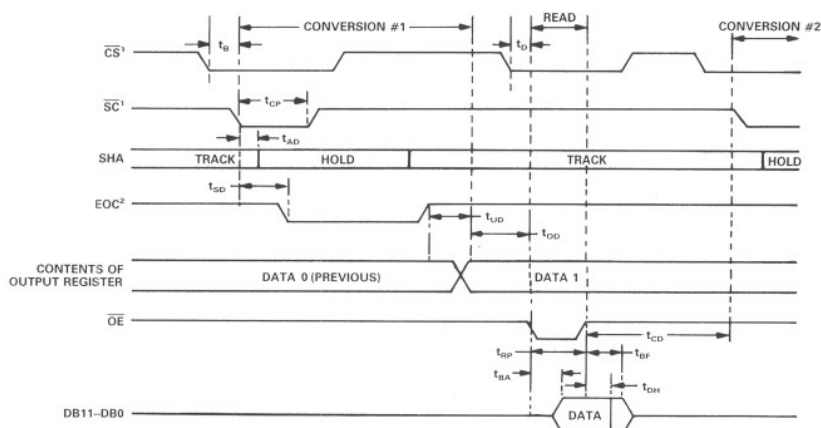
In the bipolar mode, the major carry transition (1111 1111 1111 to 0000 0000 0000) should occur at an analog value  $1/2$  LSB below analog ground. Bipolar zero error is the deviation of the actual transition from that point. This error can be adjusted as discussed in the Input Connections and Calibration Section.

## GAIN ERROR

The last transition should occur at an analog value  $1 1/2$  LSB below the nominal full scale (9.9963 volts for a 0-10V range, 4.9963 volts for a  $\pm 5\text{V}$  range). The gain error is the deviation of the actual level at the last transition from the ideal level with the zero error trimmed out. This error can be adjusted as shown in the Input Connections and Calibration Section.



## Timing



NOTES  
1. IF SYNC = LOW, STATE OF CS DOES NOT AFFECT CONVERT OPERATION. IF SYNC = HIGH, CS SHOULD BE BROUGHT LOW BEFORE SC TO START A CONVERSION. SEE THE START CONVERSION TRUTH TABLE FOR DETAILS.  
2. EOC IS A TRISTATE OUTPUT. SEE CONVERSION STATUS TRUTH TABLE FOR DETAILS.

Figure 7. AD1678 Conversion Start & Output Enable Timing (12-Bit Read Mode)

### CONVERSION CONTROL

In synchronous mode (SYNC = HIGH), both Chip Select ( $\overline{CS}$ ) and Start Convert ( $\overline{SC}$ ) must be brought LOW to start a conversion.  $\overline{CS}$  should be LOW 50nsec ( $t_b$ ) before  $\overline{SC}$  is brought LOW. In asynchronous mode (SYNC = LOW), a conversion is started by bringing  $\overline{SC}$  low, regardless of the state of  $\overline{CS}$ .

In Figure 7, the Conversion Start and Output Enable Timing diagram illustrates the read-after-convert configuration. For the maximum throughput rate, see the Applications section, Figures 10a, 10b.

Before a conversion is started, End-of-Convert (EOC) is HIGH, and the sample-hold is in track mode. After a conversion is started, the sample-hold goes into hold mode and EOC goes LOW, signifying that a conversion is in progress. During the conversion, the sample-hold will go back into track mode and start acquiring the next sample.

When the conversion is finished, EOC goes HIGH and the result is loaded into the output register after a period of time  $t_{UD}$ . Bringing  $\overline{OE}$  LOW 20 nsec ( $t_D$ ) after  $\overline{CS}$  goes LOW makes the output register contents available on the output data bits (DB11-DB0). A period of time,  $t_{CD}$ , is required after  $\overline{OE}$  is brought HIGH before the next  $\overline{SC}$  instruction is issued. This is to allow internal logic states to reset and to guarantee minimum aperture jitter for the next conversion.

In track mode, the sample-hold will settle to  $\pm 0.01\%$  (12 bits) in 1 $\mu$ s maximum. The acquisition time does not affect the throughput rate as the AD1678 goes back into track mode more than 1 $\mu$ s before the next conversion. In multichannel systems, the input channel can be switched as soon as EOC goes LOW if the maximum throughput rate is needed.

If  $\overline{SC}$  is held LOW, the AD1678 will convert continuously and the circuit of Figure 10a should be utilized.

### CONVERSION TIMING ( $T_{min}$ to $T_{max}$ )

Specification	Min	Max	Units
$t_{CP}$ Convert Pulse Width	150		ns
$t_{SD}$ Status Delay	0	1	$\mu$ s
$t_{UD}$ Update Delay		200	ns
$t_{OD}$ Output Delay	0		ns
$t_{CD}$ Conversion Delay	150		ns
$t_{RP}$ Read Pulse Width <sup>1</sup>	100		ns
$t_{BA}$ Access Time <sup>2</sup>		100	ns
$t_{DH}$ Data Hold	10		ns
$t_{BF}$ Float Delay <sup>3</sup>		80	ns
$t_{AD}$ Aperture Delay	5	20	ns
$t_B$ $\overline{SC}$ Delay	50		ns
$t_D$ $\overline{OE}$ Delay	20		ns

#### NOTES

<sup>1</sup>12-bit read mode.

<sup>2</sup>Measured from the falling edge of  $\overline{OE}$  (1.4V) to the time at which the data lines cross 2.4V or 0.4V.

<sup>3</sup>Measured from the rising edge of  $\overline{OE}$  (1.4V) to the time at which the output voltage changes by 0.5V.

### START CONVERSION TRUTH TABLE

	INPUTS			STATUS
	SYNC	$\overline{CS}$	$\overline{SC}$	
Synchronous Mode	1	1	X	No Conversion
	1	0	$\downarrow$	Start Conversion
	1	$\downarrow$	0	Start Conversion (Not Recommended)
	1	0	0	Continuous Conversion
Asynchronous Mode	0	X	1	No Conversion
	0	X	$\downarrow$	Start Conversion
	0	X	0	Continuous Conversion

#### NOTES

1 = HIGH voltage level.

0 = LOW voltage level.

X = Don't care.

$\downarrow$  = HIGH to LOW transition. Must stay low for  $t = t_{CP}$ .

### CONVERSION STATUS TRUTH TABLE

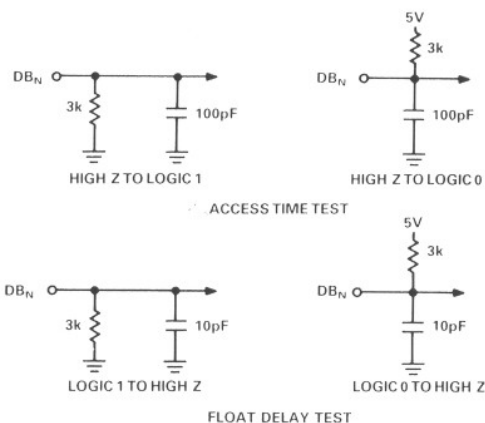
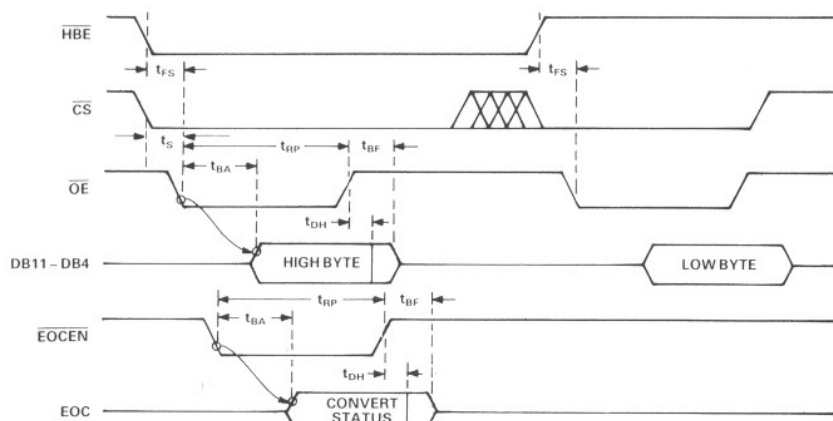
	INPUTS			OUTPUT	STATUS
	SYNC	$\overline{CS}$	EOCEN	EOC	
Synchronous Mode	1	0	0	0	Converting
	1	0	0	1	Not Converting
	1	1	X	High Z	Either
	1	X	1	High Z	Either
Asynchronous Mode	0	X	0	0	Converting
	0	X	0	1	Not Converting
	0	X	1	High Z	Either

#### NOTES

1 = HIGH voltage level.

0 = LOW voltage level.

X = Don't care.



AD1678 Output Timing (8-Bit Read Mode)

Load Circuits for Bus Timing Specifications

## OUTPUT ENABLE OPERATION

The data bits (DB11-DB0) are tristate outputs that are enabled by Chip Select ( $\overline{CS}$ ) and Output Enable ( $\overline{OE}$ ).  $\overline{CS}$  should be LOW 20ns ( $t_S$ ) before  $\overline{OE}$  is brought LOW. Bits DB1 (R/L) and DB0 (HBE) are bidirectional. In 12-bit mode they are data output bits. In 8-bit mode they are inputs that define the format of the output register.

In 12-bit mode ( $12/\overline{8} = \text{HIGH}$ ), a single READ operation accesses all 12 output bits on DB11-DB0 for interface to a 16-bit bus.

In 8-bit mode ( $12/\overline{8} = \text{LOW}$ ), only DB11-DB4 are used as output lines onto an 8-bit bus. The output is read in two steps, with the high byte read first, followed by the low byte. High Byte Enable (HBE) controls the output sequence. The 12-bit result can be right or left justified depending on the state of R/L.

In unipolar mode (BIPOFF tied to AGND), the output coding is straight binary. In bipolar mode (BIPOFF tied to  $\text{REF}_{\text{OUT}}$ ), output coding is twos complement binary.

End-Of-Convert (EOC) is a tristate output which is enabled by End-Of-Convert ENable (EOCEN) in asynchronous mode, and by EOCEN and  $\overline{CS}$  in synchronous mode.

Output Enable ( $\overline{OE}$ ) must be toggled to update data in the output register.

## OUTPUT ENABLE TRUTH TABLES

### 12-BIT MODE ( $12/\overline{8} = \text{HIGH}$ )

INPUTS	OUTPUT
( $\overline{CS}$ U $\overline{OE}$ )	DB11-DB0
1	High Z
0	Enable 12-Bit Output

### 8-BIT MODE ( $12/\overline{8} = \text{LOW}$ )

	INPUTS			OUTPUTS									
	R/L	HBE	( $\overline{CS}$ U $\overline{OE}$ )	DB11 . . . DB4									
Unipolar Mode	X	X	1	High Z									
	1	0	↓	0	0	0	0	a	b	c	d		
	1	1	↓	e	f	g	h	i	j	k	l		
	0	0	↓	a	b	c	d	e	f	g	h		
Bipolar Mode	0	1	↓	i	j	k	l	0	0	0	0		
	1	0	↓	a	a	a	a	a	b	c	d		
	1	1	↓	e	f	g	h	i	j	k	l		
	0	0	↓	a	b	c	d	e	f	g	h		
	0	1	↓	i	j	k	l	0	0	0	0		

#### NOTES

1 = HIGH voltage level.

0 = LOW voltage level.

X = Don't care.

U = Logical OR.

a = MSB.

l = LSB.

↓ = HIGH to LOW transition. Must stay low for  $t = t_{RP}$ .

## OUTPUT ENABLE TIMING ( $T_{\text{min}}$ to $T_{\text{max}}$ )

Specification	Min	Max	Units
$t_{FS}$ Format Setup	60		ns
$t_{RP}$ Read Pulse Width <sup>1</sup>	150		ns
$t_{BA}$ Access Time <sup>2</sup>		100	ns
$t_{BF}$ Float Delay <sup>3</sup>		80	ns
$t_{DH}$ Data Hold	10		ns
$t_S$ $\overline{OE}$ Delay	20		ns

#### NOTES

<sup>1</sup>8-bit read mode.

<sup>2</sup>Measured from the falling edge of  $\overline{OE}$  (1.4V) to the time at which the data lines cross 2.4V or 0.4V.

<sup>3</sup>Measured from the rising edge of  $\overline{OE}$  (1.4V) to the time at which the output voltage changes by 0.5V.

## 12-BIT MODE CODING FORMAT (1 LSB = 2.44mV)

Unipolar Coding (Straight Binary)		Bipolar Coding (Twos Complement)	
$V_{IN}$	Output Code	$V_{IN}$	Output code
0	000...0	-5.000V	100...0
5.000V	100...0	-0.002V	111...1
9.9964V	111...1	0	000...0
		+2.500V	010...0
		+4.9964	011...1



## AD1678 PIN DESCRIPTION

Symbol	Pin No.	Type	Name and Function
AGND	7	P	Analog Ground.
AIN	6	AI	Analog Signal Input.
BIPOFF	10	AI	Bipolar Offset. Connect to AGND for +10V input unipolar mode and straight binary output coding. Connect to $REF_{OUT}$ through 50 $\Omega$ resistor for $\pm 5V$ input bipolar mode and twos complement binary output coding. See Figures 8 and 9.
$\overline{CS}$	4	DI	Chip Select. Active LOW.
DGND	14	P	Digital Ground
DB11-DB4	26-19	DO	Data Bits 11 through 4. In 12-bit format (see 12/8 pin), these pins provide the upper 8 bits of data. In 8-bit format, these pins provide all 12 bits in two bytes (see R/L pin). Active HIGH.
DB3, DB2	18, 17	DO	Data Bits 3 and 2. In 12-bit format, these pins provide Data Bit 3 and Data Bit 2. Active HIGH. In 8-bit format they are undefined and should be tied to $V_{DD}$ .
DB1 (R/L)	16	DO	In 12-bit format, Data Bit 1. Active HIGH.
DB0 (HBE)	15	DO	In 12-bit format, Data Bit 0. Active HIGH.
EOC	27	DO	End-of-Convert. EOC goes LOW when a conversion starts and goes HIGH when the conversion is finished. In asynchronous mode, EOC is an open drain output and requires an external 3k $\Omega$ pull-up resistor. See $\overline{EOCEN}$ and SYNC pins for information on EOC gating.
$\overline{EOCEN}$	1	DI	End-Of-Convert Enable. Enables EOC pin. Active LOW.
HBE (DB0)	15	DI	In 8-bit format, High Byte Enable. If LOW, output contains high byte. If HIGH, output contains low byte.
$\overline{OE}$	2	DI	Output Enable. The falling edge of $\overline{OE}$ enables DB11-DB0 in 12-bit format and DB11-DB4 in 8-bit format. Gated with $\overline{CS}$ . Active LOW.
$REF_{IN}$	9	AI	Reference Input. +5V input gives 10V full scale range.
$REF_{OUT}$	8	AO	+5V Reference Output. Tied to $REF_{IN}$ through 50 $\Omega$ resistor for normal operation.
R/L (DB1)	16	DI	In 8-bit format, Right/Left justified. Sets alignment of 12-bit result within 16-bit field. Tied to $V_{DD}$ for right-justified output and tied to DGND for left-justified output.
$\overline{SC}$	3	DI	Start Convert. Active LOW. See SYNC pin for gating.
SYNC	13	DI	Sync Control. If tied to $V_{DD}$ (synchronous mode), $\overline{SC}$ , EOC and $\overline{EOCEN}$ are gated by $\overline{CS}$ . If tied to DGND (asynchronous mode), $\overline{SC}$ and $\overline{EOCEN}$ are independent of $\overline{CS}$ , and EOC is an open drain output. EOC requires an external 3k $\Omega$ pull-up resistor in asynchronous mode.
$V_{CC}$	11	P	+12V Analog Power.
$V_{EE}$	5	P	-12V Analog Power.
$V_{DD}$	28	P	+5V Digital Power.
12/8	12	DI	Twelve/eight bit format. If tied HIGH, sets output format to 12-bit parallel. If tied LOW, sets output format to 8-bit multiplexed.

Type: AI = Analog Input.

AO = Analog Output.

DI = Digital Input (TTL and 5V CMOS compatible).

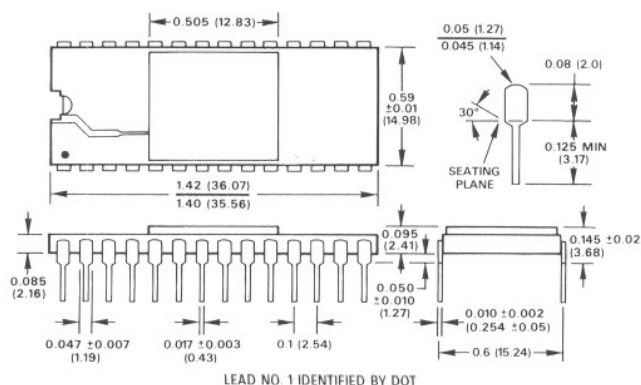
DO = Digital Output (TTL and 5V CMOS compatible). All DO pins are three-state drivers.

P = Power.

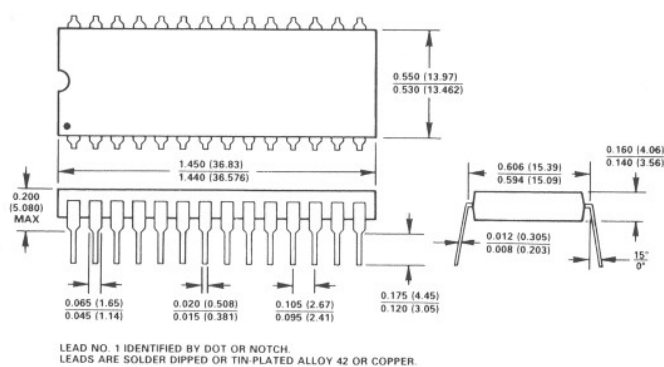
## OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

28-Pin Ceramic DIP Package (D-28A)



28-Lead Plastic DIP Package (N-28A)



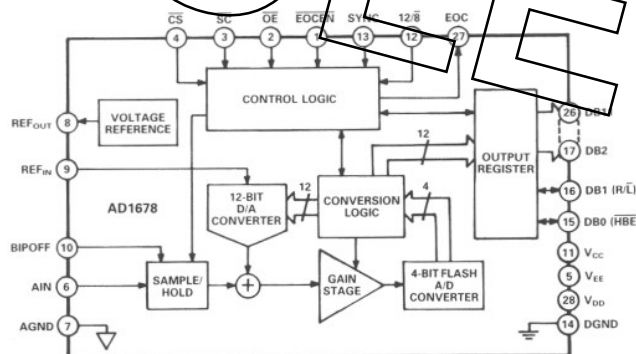
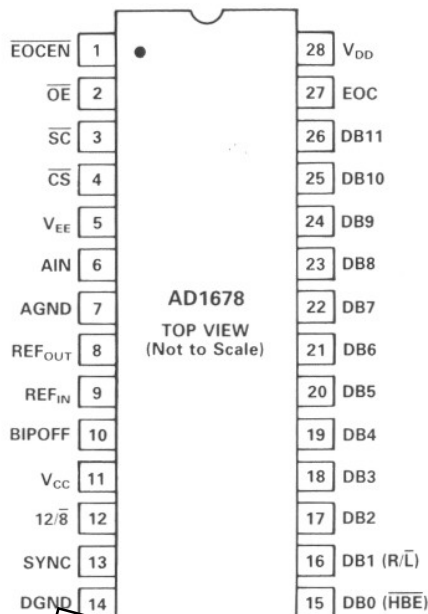


# ABSOLUTE MAXIMUM RATINGS\*

Specification	With Respect To	Min	Max	Units
$V_{CC}$	AGND	-0.3	+18	V
$V_{EE}$	AGND	-18	+0.3	V
$V_{CC}$	$V_{EE}$	-0.3	+26.4	V
$V_{DD}$	DGND	0	+7	V
AGND	DGND	-1	+1	V
AIN, REF <sub>IN</sub>	AGND	-12	+12	V
REF <sub>IN</sub>	$V_{EE}$	0	$V_{CC}$	V
REF <sub>IN</sub>	$V_{CC}$	$V_{EE}$	0	V
Digital Inputs	DGND	-0.5	+7	V
Digital Outputs	DGND	-0.5	$V_{DD} + 0.3$	V
Max Junction Temperature			175	°C
Operating Temperature				
J and K Grades		0	+70	°C
Storage Temperature		-65	+150	°C
Lead Temperature (10sec max)			+300	°C

\*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# PIN CONFIGURATION



Functional Block Diagram

# ORDERING GUIDE

Model	Package	Minimum S/N + D @ 10kHz, -0.5dB Input	Temperature Range	Price (100s)
AD1678JN	28-Pin Plastic DIP	70dB	0 to +70°C	\$38.00
AD1678KN	28-Pin Plastic DIP	72dB	0 to +70°C	\$42.00
AD1678JD	28-Pin Ceramic DIP	70dB	0 to +70°C	\$45.00
AD1678KD	28-Pin Ceramic DIP	72dB	0 to +70°C	\$50.00

# ESD SENSITIVITY

The AD1678 features input protection circuitry consisting of large "distributed" diodes and polysilicon series resistors to dissipate both high-energy discharges (Human Body Model) and fast, low energy pulses (Charged Device Model). Per Method 3015.2 of MIL-STD-883C, the AD1678 has been classified as a Category A device.

Proper ESD precautions are strongly recommended to avoid functional damage or performance degradation. Charges as high as 4000 volts readily accumulate on the human body and test equipment and discharge without detection. Unused devices must be stored in conductive foam or shunts, and the foam should be discharged to the destination socket before devices are removed. For further information on ESD precautions, refer to Analog Devices' ESD Prevention Manual.



# Application Information

## INPUT CONNECTIONS AND CALIBRATION

The AD1678 is factory trimmed to minimize offset, gain and linearity errors. In unipolar mode, the only external component that is required is a  $50\Omega \pm 1\%$  resistor. Two resistors are required in bipolar mode. If offset and gain are not critical, even these components can be eliminated.

In some applications, offset and gain errors need to be more precisely trimmed. The following sections describe the correct procedure for these various situations.

## BIPOLAR RANGE INPUTS

The connections for the bipolar mode are shown in Figure 8. In this mode, data output coding will be two's complement binary. This circuit will allow approximately  $\pm 25\text{mV}$  of offset trim range ( $\pm 10$  LSB) and  $\pm 0.5\%$  of gain trim range ( $\pm 20$  LSB).

Either or both of the trim pots can be replaced with  $50\Omega \pm 1\%$  fixed resistors if the AD1678 accuracy limits are sufficient for application. If the pins are shorted together, the additional offset and gain errors will be approximately 20 LSB.

To trim bipolar zero to its nominal value, apply a signal  $1/2$  LSB below midrange ( $-1.22\text{mV}$  for a  $\pm 5\text{V}$  range) and adjust R1 until the major carry transition is located (1111 1111 1111 to 0000 0000 0000). To trim the gain, apply a signal  $1/2$  LSB below full scale ( $+4.9963\text{V}$  for a  $\pm 5\text{V}$  range) and adjust R2 to give the last positive transition (0111 1111 1110 to 0111 1111 1111). These trims are interactive so several iterations may be necessary for convergence.

A single pass calibration can be done by substituting a bipolar offset trim (error at minus full scale) for the bipolar zero trim (error at midscale), using the same circuit. First, apply a signal  $1/2$  LSB above minus full scale ( $-4.9988\text{V}$  for a  $\pm 5\text{V}$  range) and adjust R1 until the minus full scale transition is located (1000 0000 0000 to 1000 0000 0001). Then perform the gain error trim as outlined above.

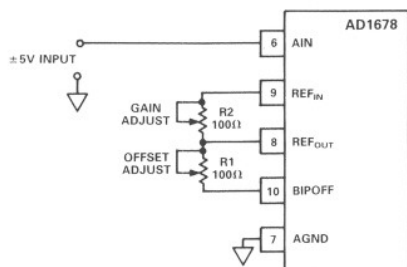


Figure 8. Bipolar Input Connections with Gain and Offset Trims

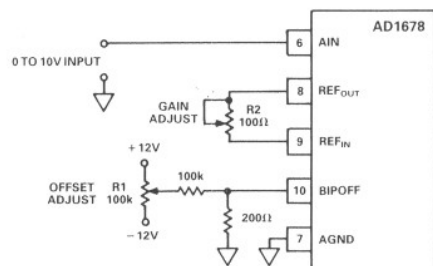


Figure 9. Unipolar Input Connections with Gain and Offset Trims

## UNIPOLAR RANGE INPUTS

The connections for the unipolar mode are shown in Figure 9. In this mode, data output coding will be straight binary. This circuit will allow approximately  $\pm 25\text{mV}$  of offset trim range ( $\pm 10$  LSB) and  $\pm 0.5\%$  of gain trim range ( $\pm 20$  LSB).

If the standard accuracy limits of the AD1678 are sufficient for the application, the gain adjust resistor (R2) can be replaced by a  $50\Omega \pm 1\%$  fixed resistor and BIPOFF can be connected to ground.

## BOARD LAYOUT

Designing with high resolution data converters requires careful attention to board layout. Trace impedance is the first issue. A  $5\text{mA}$  current through a  $0.5\Omega$  trace will develop a voltage drop of  $2.5\text{mV}$ , which is 1 LSB at the 12-bit level for a  $10\text{V}$  full scale span. In addition to ground drops, inductive and capacitive coupling need to be considered, especially when high accuracy analog signals share the same board with digital signals. Finally, power supplies need to be decoupled in order to filter out ac noise.

Analog and digital signals should not share a common path. Each signal should have an appropriate analog or digital return routed close to it. Using this approach, signal loops enclose a small area, minimizing the inductive coupling of noise. Wide PC tracks, large gauge wire, and ground planes are highly recommended to provide low impedance signal paths. Separate analog and digital ground planes are also desirable, with a single interconnection point to minimize ground loops. Analog signals should be routed as far as possible from digital signals and should cross them at right angles.

The AD1678 incorporates several features to help the user's layout. Analog pins ( $V_{EE}$ , AIN, AGND,  $\text{REF}_{\text{OUT}}$ ,  $\text{REF}_{\text{IN}}$ , BIPOFF,  $V_{CC}$ ) are adjacent to help isolate analog from digital signals. In addition, the  $10\text{M}\Omega$  input impedance of AIN minimizes input trace impedance errors. Finally, ground currents have been minimized by careful circuit architecture. Current through AGND is  $200\mu\text{A}$ , with no code dependent variation. The current through DGND is dominated by the return current for DB11-DB0 and EOC.

## SUPPLY DECOUPLING

The AD1678 power supplies should be well filtered, well regulated, and free from high frequency noise. Switching power supplies are not recommended due to their tendency to generate spikes which can induce noise in the analog system.

Decoupling capacitors should be used in very close layout proximity between all power supply pins and ground. A  $10\mu\text{F}$  tantalum capacitor in parallel with a  $0.1\mu\text{F}$  disk ceramic capacitor provides adequate decoupling over a wide range of frequencies.

An effort should be made to minimize the trace length between the capacitor leads and the respective converter power supply and common pins. The circuit layout should attempt to locate the AD1678, associated analog input circuitry and interconnections as far as possible from logic circuitry. A solid analog ground plane around the AD1678 will isolate large switching ground currents. For these reasons, the use of wire wrap circuit construction is not recommended; careful printed circuit construction is preferred.



## GROUNDING

If a single AD1678 is used with separate analog and digital ground planes, connect the analog ground plane to AGND and the digital ground plane to DGND keeping lead lengths as short as possible. Then connect AGND and DGND together at the AD1678. If multiple AD1678s are used or the AD1678 shares analog supplies with other components, connect the analog and digital returns together once at the power supplies rather than at each chip. This prevents large ground loops which inductively couple noise and allow digital currents to flow through the analog system.

## 200KSPS READ APPLICATION

In applications requiring the maximum throughput of the AD1678, the read circuit of Figure 10a is recommended. The converter is operated in its 12-bit, parallel-read mode with  $\overline{OE}$  derived from EOC through an inverter. On the falling edge of  $\overline{OE}$ , data from the previous conversion is latched in the converter's output register and is available on the data bus 100ns ( $t_{BA}$ ) later. An external latch can then hold the data if retiming is necessary. Note that in this configuration, a one-sample pipeline delay is introduced since the data accessed corresponds to the previous conversion, rather than the most recent (see Figure 10b).

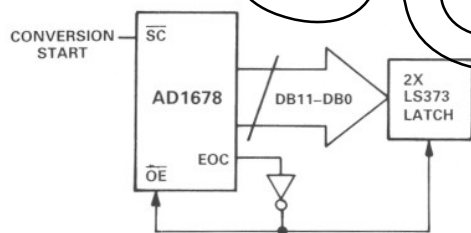


Figure 10a. 200KSPS Output Configuration

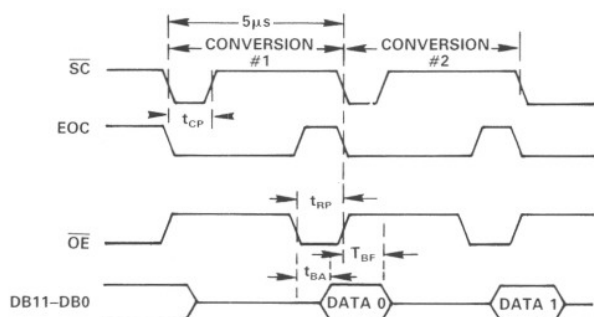


Figure 10b. 200KSPS 12-Bit Read Timing

## INTERFACING THE AD1678 TO MICROPROCESSORS

The I/O capabilities of the AD1678 allow direct interfacing to general purpose and DSP microprocessor buses. The asynchronous conversion control feature allows complete flexibility and control with minimal external hardware.

The following examples illustrate typical AD1678 interface configurations.

## AD1678 TO TMS320C25

In Figure 11 the AD1678 is mapped into the TMS320C25 I/O space. AD1678 conversions are initiated by issuing an OUT instruction to Port 8. EOC status and the conversion result are read in with an IN instruction to Port 8. A single wait state is inserted by generating the processor READY input from  $\overline{IS}$ , Port 8 and MSC. This configuration supports processor clock speeds of 20MHz and is capable of supporting processor clock speeds of 40MHz if a NOP instruction follows each AD1678 read instruction.

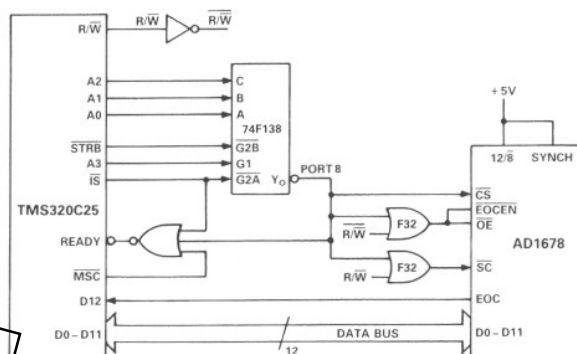


Figure 11. AD1678 to TMS320C25 Interface

## AD1678 TO 80186

Figure 12 shows the AD1678 interfaced to the 80186 microprocessor. This interface allows the 80186's built-in DMA controller to transfer the AD1678 output into a RAM based FIFO buffer of any length, with no microprocessor intervention.

In this application the AD1678 is configured in the asynchronous mode, which allows conversions to be initiated by an external trigger source independent of the microprocessor clock. After each conversion, the AD1678 EOC signal generates a DMA request to Channel 1 (DRQ1). The subsequent DMA READ operation resets the interrupt latch. The system designer must assign a sufficient priority to the DMA channel to ensure that the DMA request will be serviced before the completion of the next conversion. This configuration can be used with 6MHz and 8MHz 80186 processors.

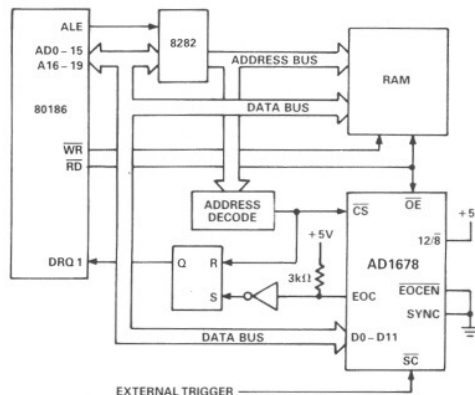


Figure 12. AD1678 to 80186 DMA Interface

### AD1678 TO Z80

The AD1678 can be interfaced to the Z80 processor in an I/O or memory mapped configuration. Figure 13 illustrates an I/O configuration, where the AD1678 occupies several port addresses to allow separate polling of the EOC status and reading of the data. The lower address bit, A0, is used to select the high and low order bytes of the result. The AD1678 R/L line is tied HIGH, resulting in right justified output data.

A useful feature of the Z80 is that a single wait state is automatically inserted during I/O operations, allowing the AD1678 to be used with Z80 processors having clock speeds up to 8MHz.

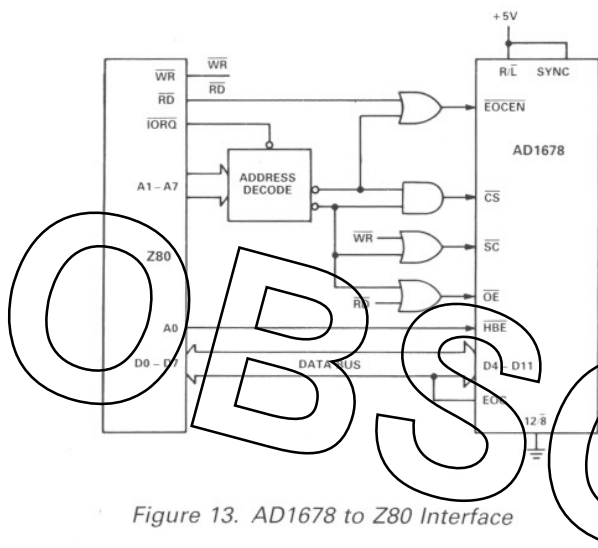


Figure 13. AD1678 to Z80 Interface

### AD1678 TO ANALOG DEVICES ADSP-2100

Figure 14 demonstrates the AD1678 interfaced to an ADSP-2100. With a clock frequency of 8MHz, and instruction execution in one 125ns cycle, the digital signal processor will support the AD1678 data memory interface with a single wait state.

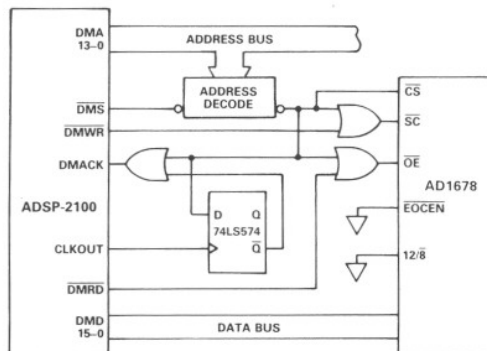


Figure 14. AD1678 to ADSP-2100 Interface

At the beginning of the data memory access cycle, the processor provides a 14-bit address on the DMA bus. The DMS signal is then asserted, enabling a LOW address decode and the AD1678 CS. The processor issues DMWR which is gated with the decoded address to start conversion. The LOW decoded address is also OR'ed with the Q output of a D flip-flop to pull DMACK LOW. This forces the ADSP-2100 into a wait state for 1 clock cycle. The rising edge of CLKOUT latches Q HIGH bringing DMACK HIGH. The conversion is complete 5µs later. The processor can now start a data memory access cycle to read data. For this cycle the DMRD and LOW decoded address are OR'ed to generate OE for the converter. Once again, a single wait state is inserted allowing data to be read from the bus.